



CENTRE NATIONAL D'ÉTUDES SPATIALES

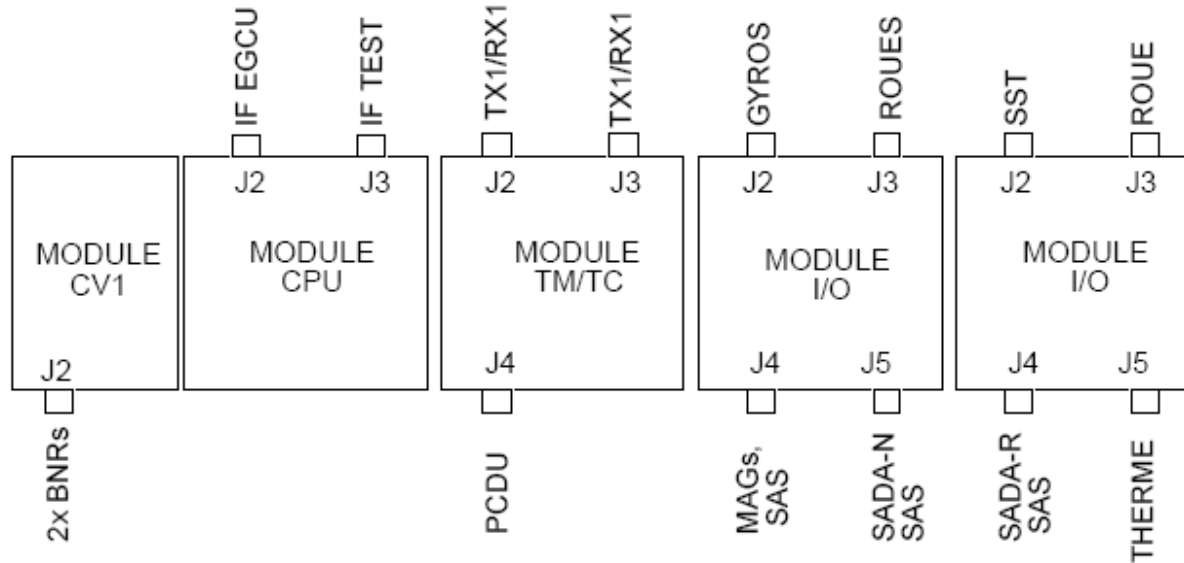
***Some CNES electronic activities using
Microcontrollers***

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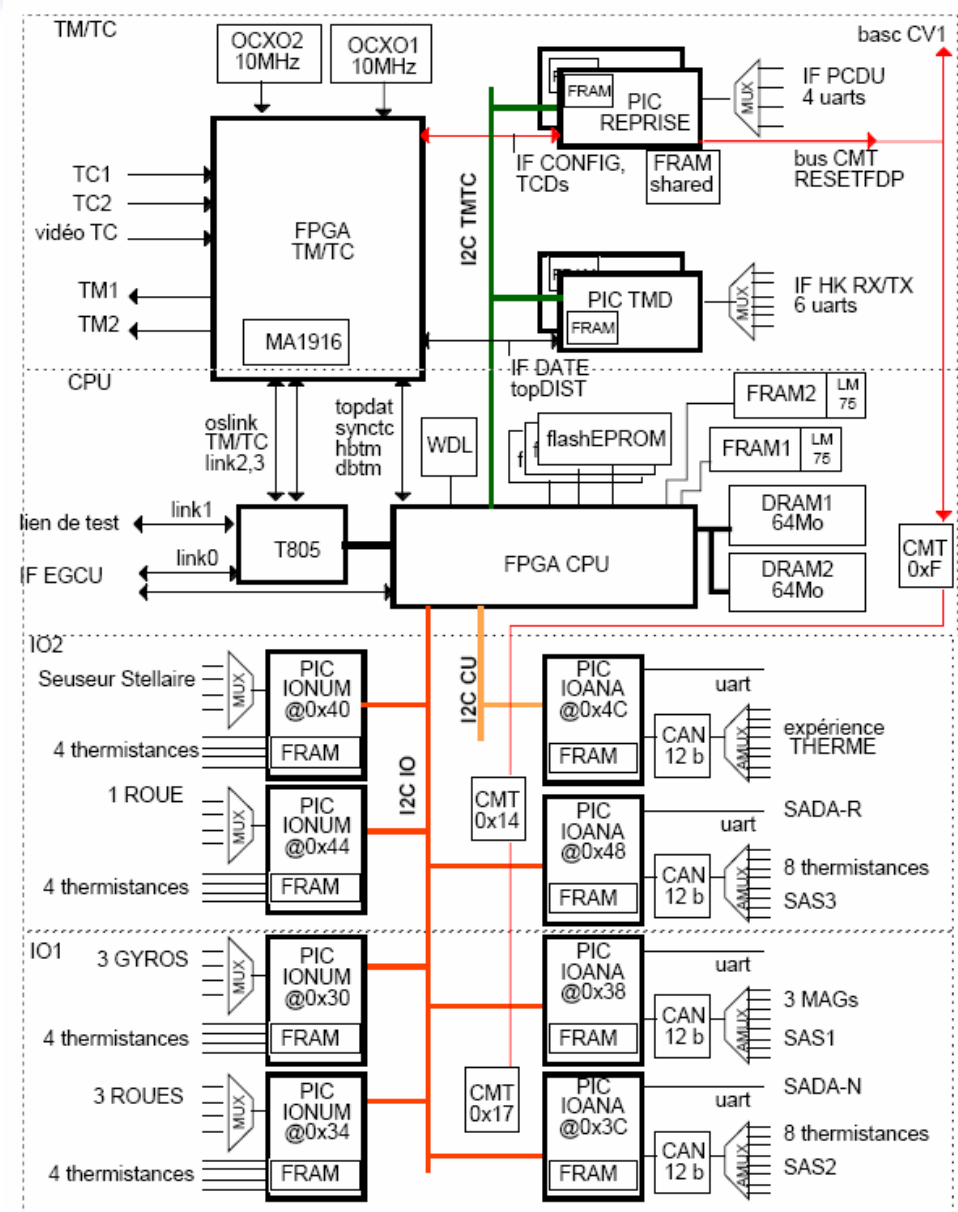
Summary

- MYRIADE Heritage on Microcontrollers
- Space Evaluation on Microcontrollers
- Thermal Control and Servitude Bus (TCSBUS)
- Li-Ion Battery Balancing Electronic (LIBBE)



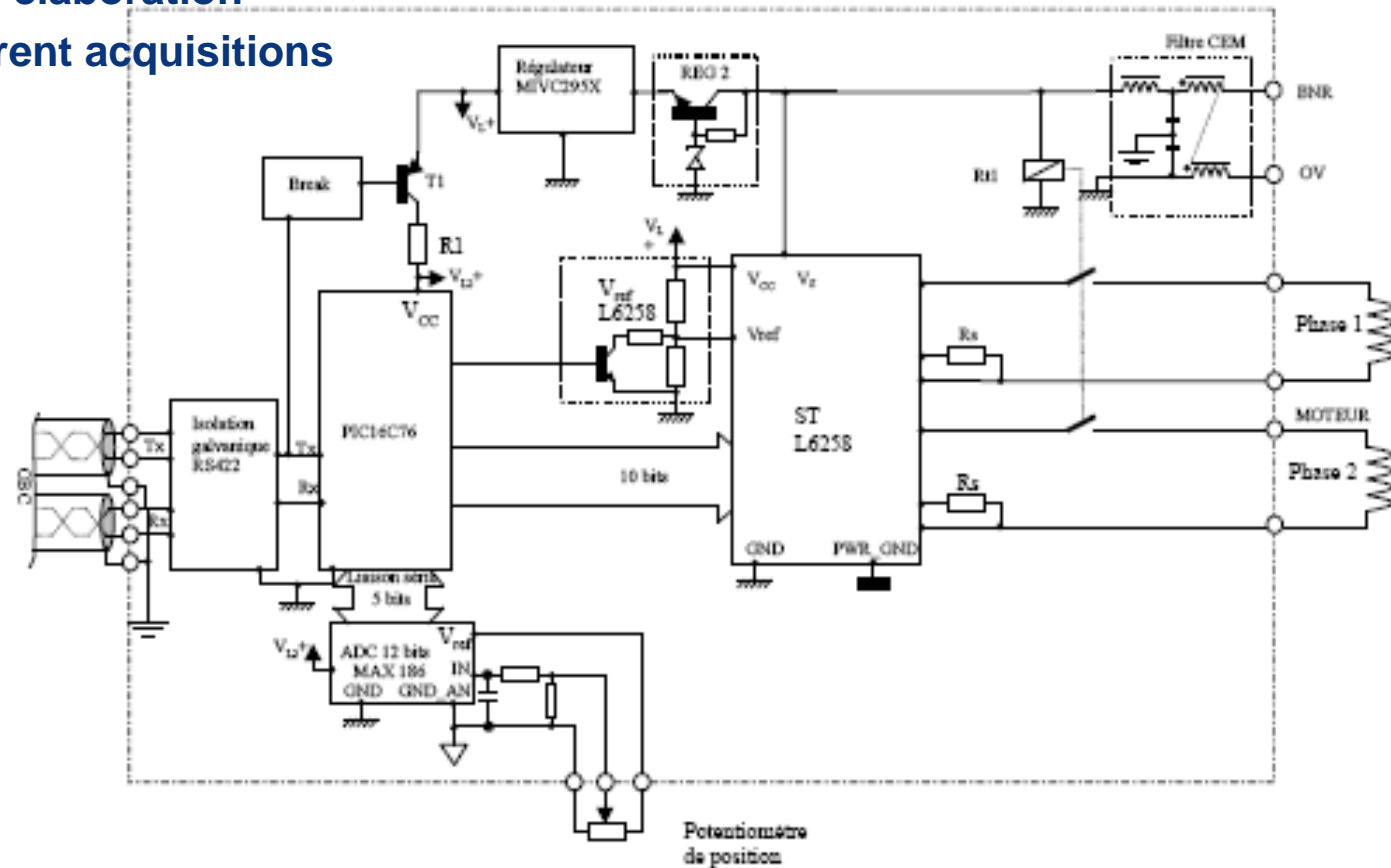
■ OBC architectures :

- ◆ **PIC16C76** from MICROCHIP
- ◆ **PIC16C76** tested in radiation and evaluated for space.
- ◆ **Protections :**
 - PIC supply current limited (Latch-up)
 - De-latch circuit
 - External particular watchdog
- ◆ **I/O modules :**
 - PIC between internal I2C bus and external I/F
 - Digital I/O
 - Analog I/O
- ◆ **TM/Tc module :**
 - Redounded PICs I/F with PCDU
 - Redounded PICs I/F with RX/TX



■ SADM MYRIADE :

- ◆ PIC16C76
- ◆ Electronic command of the drive mechanism
- ◆ Interface dialog with OBC
- ◆ Motor Phase references elaboration
- ◆ Motor position and current acquisitions



- **Excellent behavior in flight**
- **8 satellites in orbit :**
 - ◆ **DEMETER, PARASOL, 4 ESSAIM (2004)**
 - ◆ **SPIRAL (2007)**
 - ◆ **PICARD (2010)**
- **No anomaly on Microcontrollers**

■ NEW generation of MYRIADE products :

- ◆ **Obsolescence of PIC16C76**
- ◆ **Find a new PIC reference for MYRIADE line of product (OBC, SADM, others...)**

■ Space evaluation :

- ◆ **CNES R&T will start on space evaluation of Microcontrollers**

■ New applications :

- ◆ **Decentralized I/F units**
 - Sensor network
 - Discrete standards interfaces
 - Active Thermal control
- ◆ **Battery management**

■ Preliminary trade-off on microcontrollers :

- ◆ **CNES internal preliminary evaluation on Microcontroller needs**
- ◆ **Replacement of the Microchip PIC16C76 used by MYRIADE**
- ◆ **First references chosen : Microchip PIC18LF2620, PIC18LF2820, PIC18LF4620, PIC18LF4820**
 - Pin compatible for MYRIADE OBC (PIC18LF2620, PIC18LF2820)
 - Same supply voltage
 - Identification of the main performance needed for new applications
 - Limit the complexity compared of the new PIC available by MICROCHIP (PIC32)
 - Similar technologies with 16C family (radiation aspects)
- ◆ **Application : Low cost missions which accept commercial components.**

■ R&T Studies on space evaluation :

◆ Strengthening of the Microcontroller

- Protection against Latch-up
- Memories protection against SEU
- Recovery after transients
- Re programming
- Design of all these protection functions around the Microcontroller
- Packaging

◆ Radiation tests :

- Breadboard including all the protections and recovery circuits
- Microcontroller operating with an adequate software
- Test of the maximum internal functions of the Microcontroller (RAM, EEPROM, I/O, ADC, UART, clock, I2C Bus, CAN Bus...)

◆ Planning : 2011-2012

◆ Outputs :

- PIC reference available for space application
- Design of protection mechanisms
- User manual for space application

- **TCSBUS : Thermal Control and Servitude BUS**

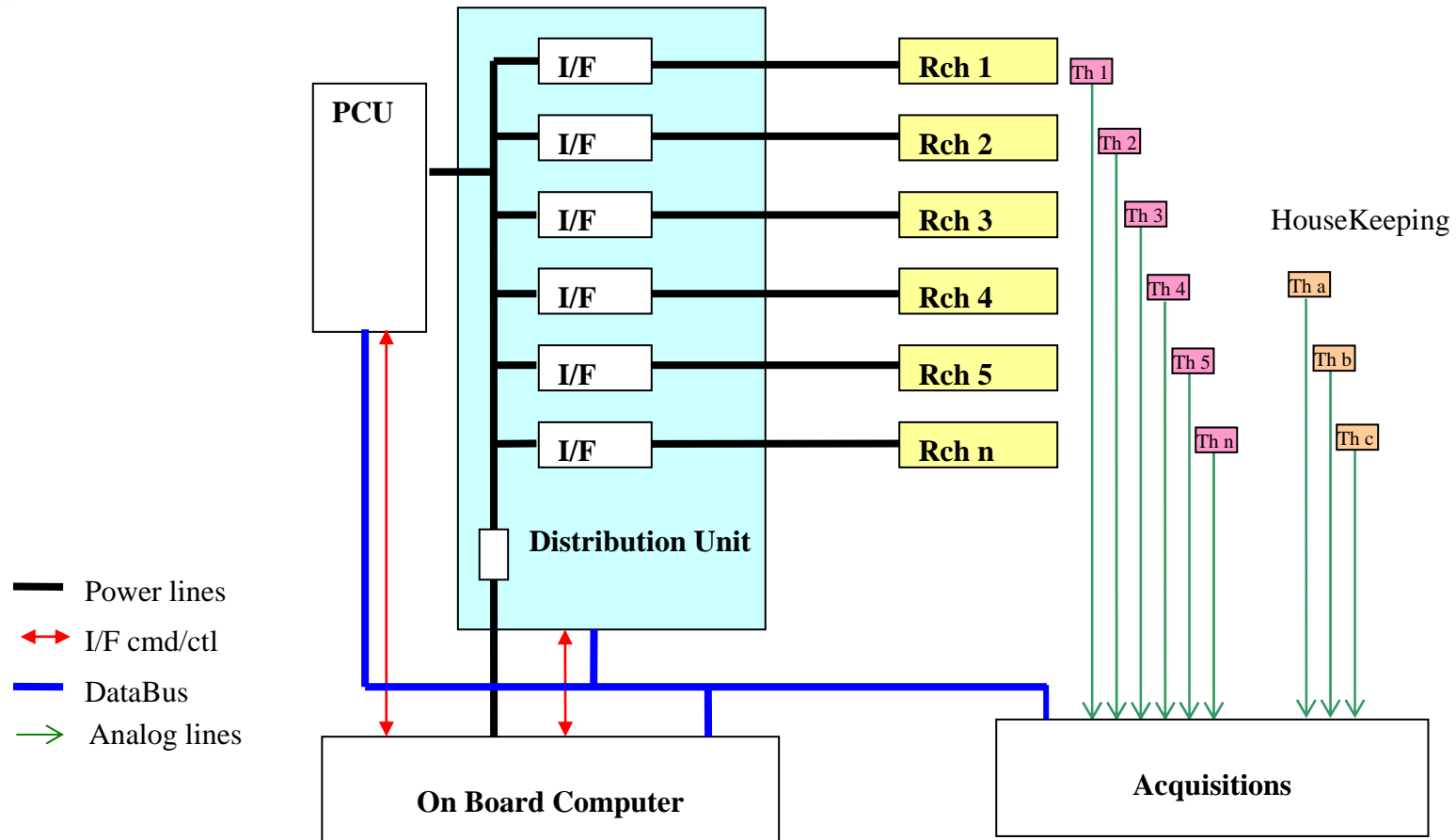
■ Harness reduction :

- ◆ R&T 2007 CNES ASTRIUM : “harness reduction”
- ◆ From classical centralized architecture to decentralized
- ◆ Reduction by 3 of the harness
- ◆ Need decentralized interface box or terminals
- ◆ Good candidate for harness reduction : active thermal control

■ R&T TCSBUS:

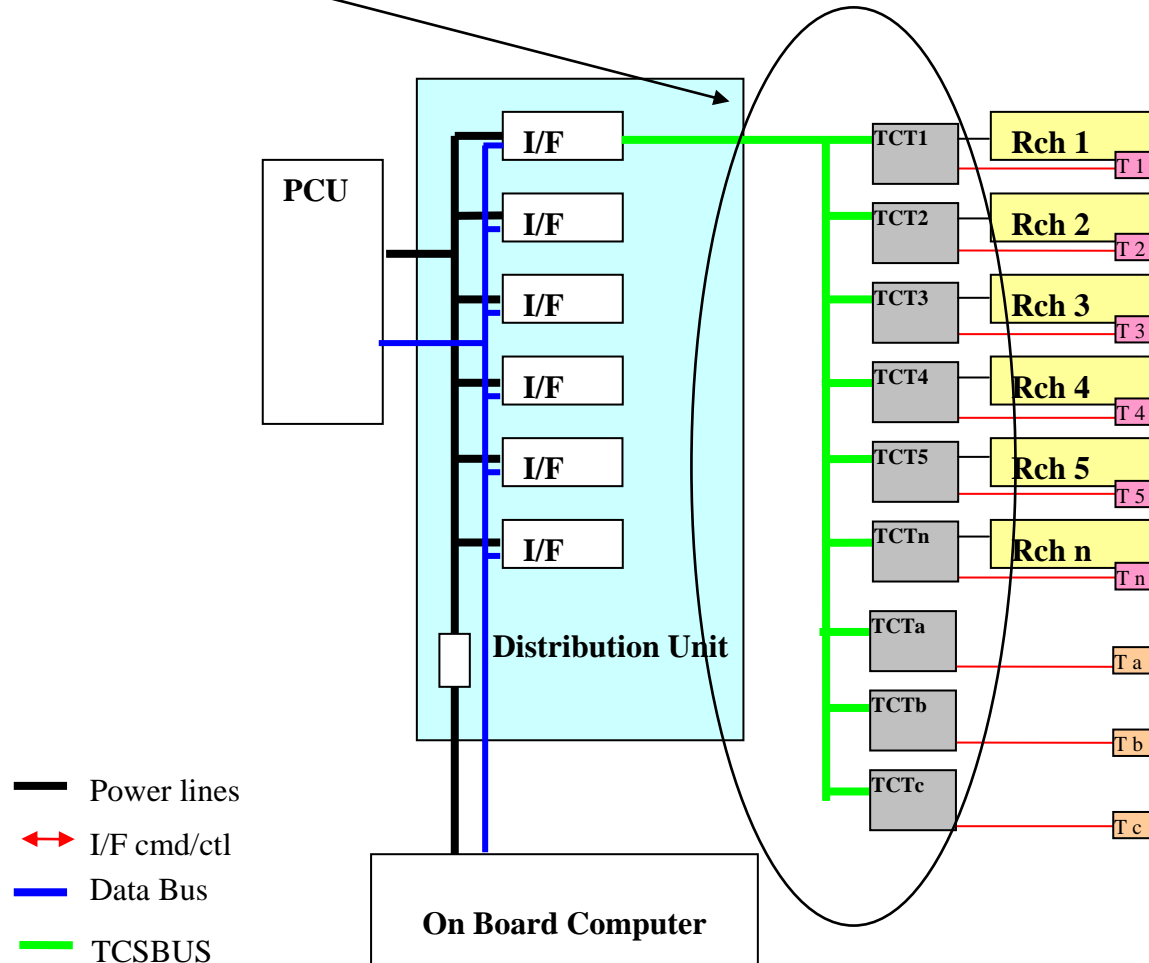
- ◆ R&T 2009 studies between CNES and SOPRA/DELTA TECHNOLOGIES
- ◆ Decentralized architecture of an active thermal control and servitude based on low baud rate data bus
- ◆ Planning :
 - 06/2010 : Architecture trade-OFF
 - 12/2010 : Detailed Design and realization of elegant bread-board
 - 06/2011 : Tests revue

■ Example of active thermal control with basic centralized architecture :



■ Example of active thermal control with decentralized architecture :

◆ TCSBUS studied



■ Architecture of the TCSBUS :

■ TCS Bus :

- ◆ 2 wires for Databus RS485,
- ◆ 2 wires for 5V supply,
- ◆ 2 wires for power distribution and heater supplies
- ◆ up to 16 terminals connected
- ◆ Direct interface with MYRIADE OBC and PCDU

■ Bus controller :

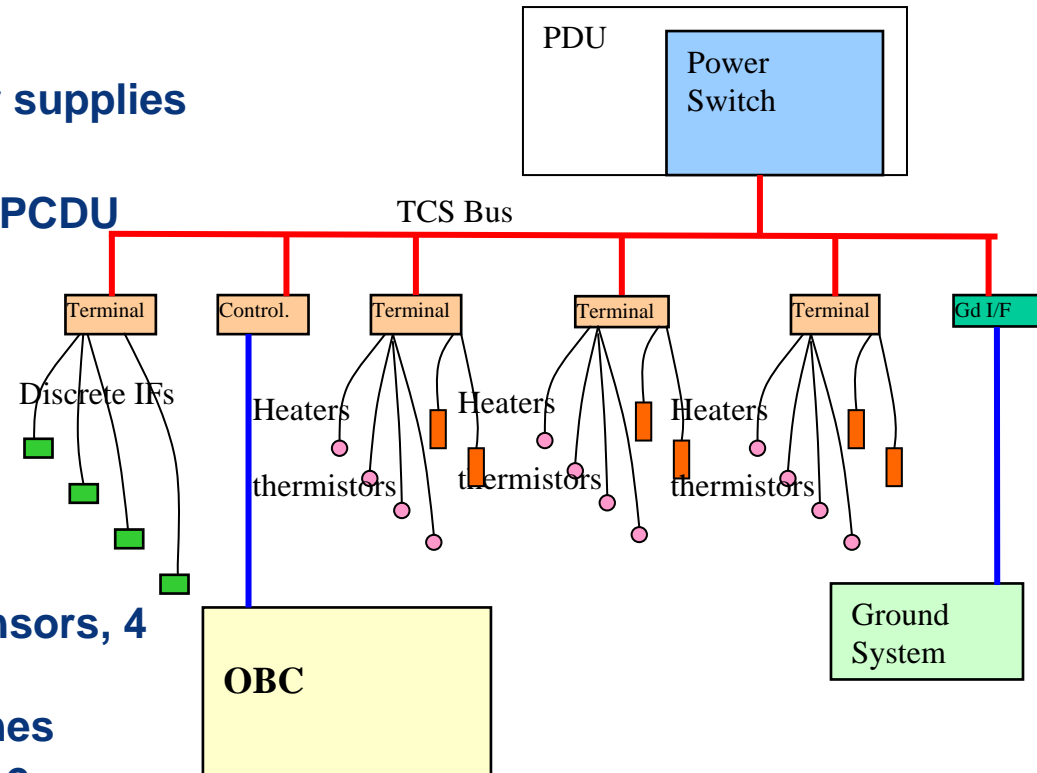
- ◆ I/F with OBC,
- ◆ Master
- ◆ DCDC converter

■ Terminals :

- ◆ I/F with users
- ◆ Thermal Control Terminal : 8 thermal sensors, 4 heaters
- ◆ Power Distribution Terminal : 4 power lines
- ◆ Discrete Standard Interfaces Terminal : 12 discrete I/O

■ Ground I/F

- ◆ Specific Terminal like a Bus controller



■ High integration

- ◆ Terminal and Bus Controllers lower than 60x60x20mm (not optimized)
- ◆ Connector on the Bus (μ COMP SOURIAU connectors)

■ Generic internal smart component :

- ◆ Interface and Communication between BC and Terminals through the DATABUS (RS485) : UART
- ◆ Analog and Digital acquisitions from users interfaces : ADC 10bits
- ◆ Low discrete signal command to users
- ◆ Power switch commands for thermal control heaters or equipments
- ◆ Data processing
- ◆ Data storage
- ◆ Calibration curves

■ Microcontrollers

- ◆ Heritage on MYRIADE OBC using Microchip PIC16C76
- ◆ Microchip PIC18F family for TCSBUS

■ Main required functions of terminals :

Required by terminals							
	Program memory FLASH (bytes)	RAM (bytes)	EEPROM (bytes)	ADC	I/O	Peripherals	Voltage
Bus Controller	30k	1500	256	5	19	2 UART	2V to 5.5V
Thermal Control Terminal	25k	1850	256	7	35	1 UART	2V to 5.5V
Discrete Interfaces Terminal			256	9	36	1 UART	2V to 5.5V
Power Distribution Terminal			256	10	27	1 UART	2V to 5.5V

■ Generic Microcontroller characteristics :

- ◆ 4 Preselected references
- ◆ CNES internal preliminary trade-off
- ◆ **PIC18LF4620 QFN44**

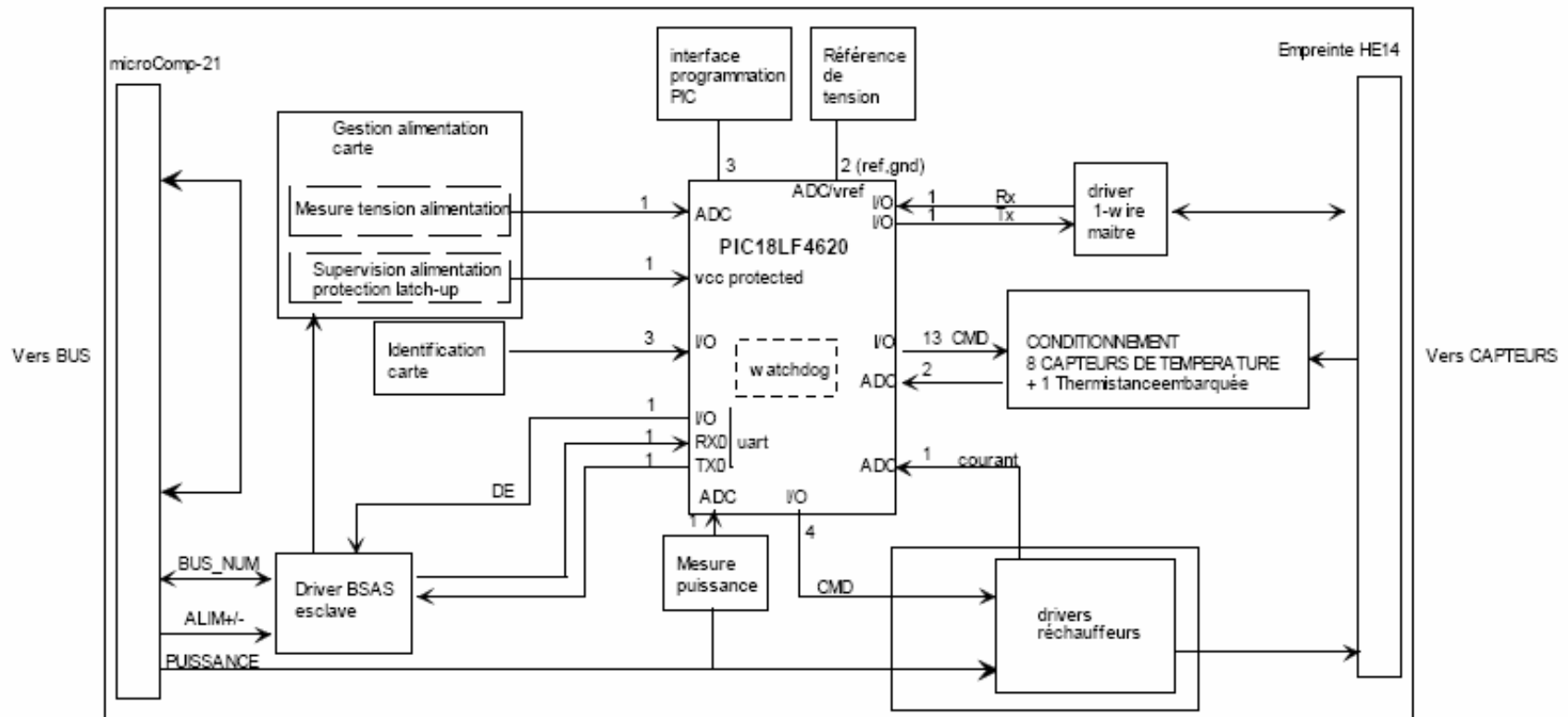
	Program memory Flash (KB)	RAM Bytes	EEPROM (bytes)	Timer	ADC	Pin count	Périphériques	Voltage
PIC18LF2620 <i>in production</i> [Maquette Contrôleur de bus]	64	3.968	1024	1 x 8bits 3x16bits	10CH, 10 bit	28 SPDIP, SOIC	1-A/E/USART, 1- MSSP(SPI/I2C)	2 à 5.5V
PIC18LF6722 <i>in production</i> [Maquette CTS]	128	3.936	1024	2 x 8bits 3x16bits	12CH, 10-bit	64 TQFP	2-A/E/USART, 2- MSSP(SPI/I2C)	2 à 5.5V
PIC18LF2520 <i>in production</i>	32	1.536	256	1 x 8bits 3x16bits	9CH, 10 bits	28 SPDIP, SOIC 28 QFN	1-A/E/USART, 1- MSSP(SPI/I2C)	2 à 5.5V
PIC18LF4620 <i>in production</i>	64	3.968	1024	1 x 8bits 3x16bits	13CH, 10 bits	40-Pin PDIP 44-Pin TQFP 44-Pin QFN	1-A/E/USART, 1- MSSP(SPI/I2C)	2 à 5.5V
PIC18LF4680 <i>in production</i>	64	3328	1024	1 x 8bits 3x16bits	11CH, 10 bits	40-Pin PDIP 44-Pin TQFP 44-Pin QFN	1-A/E/USART, 1- MSSP(SPI/I2C)	2 à 5.5V

■ Microcontroller protections :

- ♦ Latch-up protection : A current limitation on the power supply is implemented in order to limit the dissipation inside the Microcontroller and then the destruction.
- ♦ De-latch circuit in order to re-initialize de Microcontroller after a latch up or an SEE : An external circuit cut OFF the Microcontroller supply during few milliseconds.
- ♦ Discrete external watchdog : One task of the μ C is to generate a periodic signal on one I/O port. In case of no activity inside the PIC this signal is not refreshed then the discrete external circuit initializes the Microcontroller by switching OFF and ON its supply.

Thermal Control Terminal internal architecture :

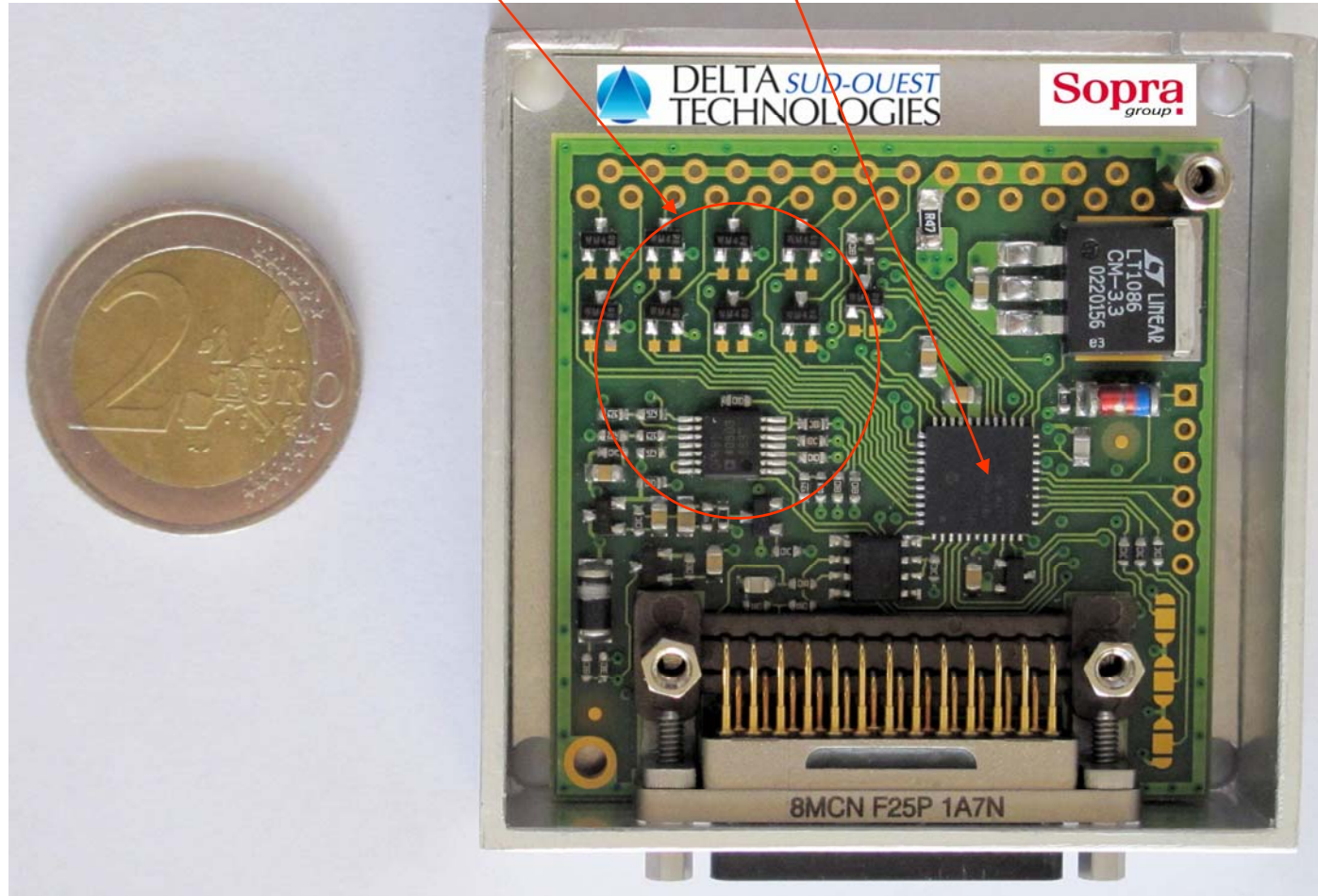
- ◆ 8 thermal sensor input acquisitions
- ◆ 4 power switched lines for heaters
- ◆ Other acquisitions : internal temperature, supply voltage, power voltage, heater currents
- ◆ 1-WIRE bus output (possibility to connect 1-Wire digital thermal sensor network)



- Thermal control terminal:

Thermal acquisition

μ C

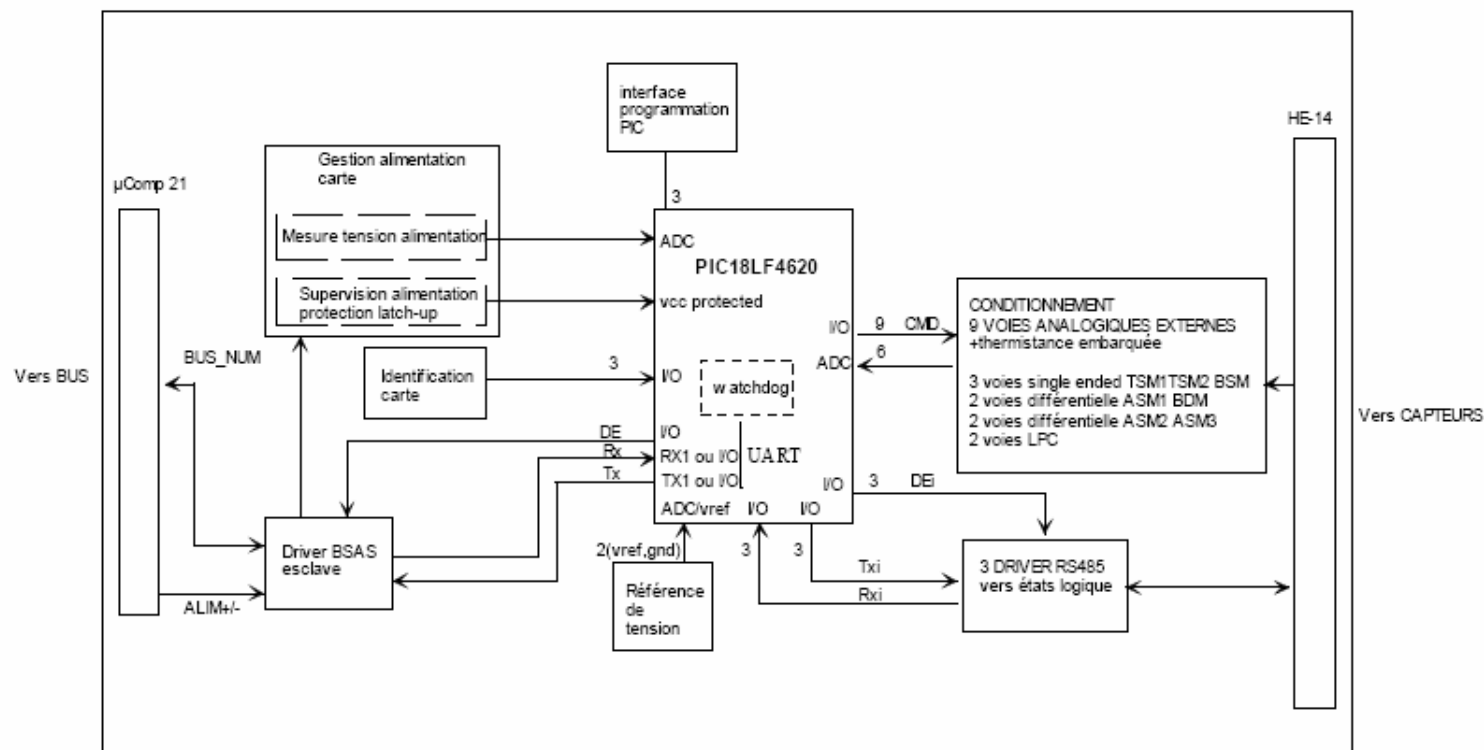


Top view

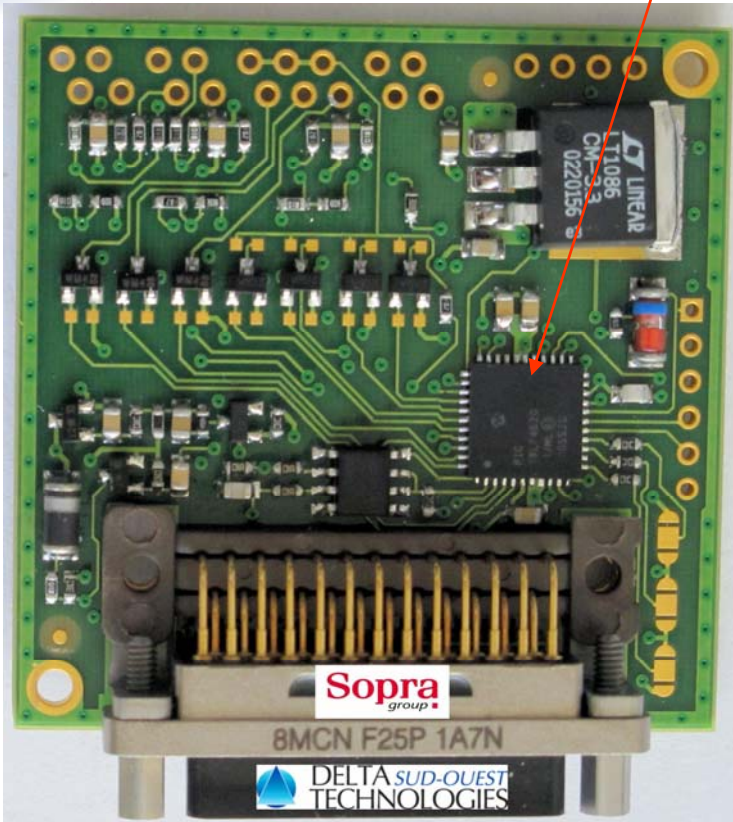
■ Discrete Interfaces terminal internal architecture :

◆ 11 external I/O :

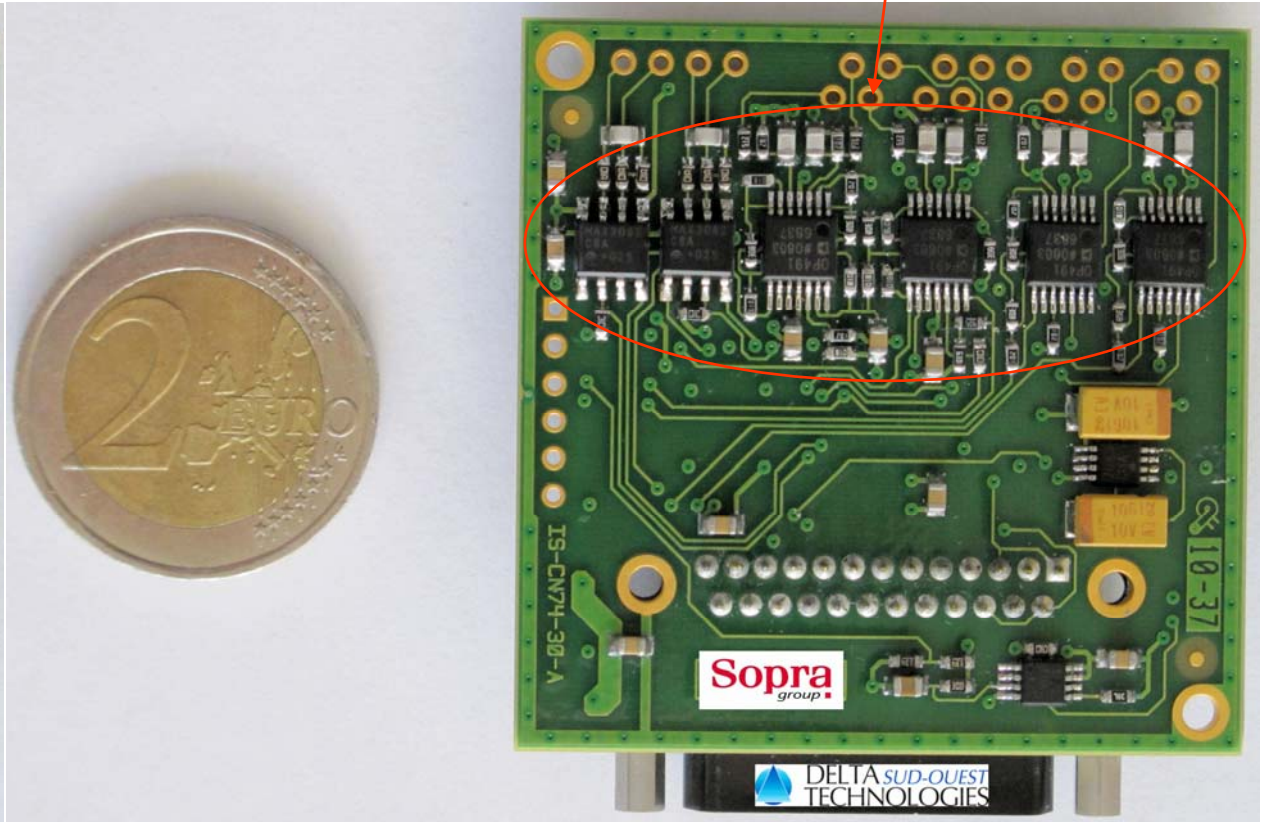
- 2 SBDL configurable input or output
- 3 analog acq. configurable TSM1 (thermal sensor type 1), TSM2 or BSM (switch status)
- 2 analog acq. configurable ASM1 (0/+ 5V) or BDM (single digital)
- 2 analog acq. configurable ASM2 (+/-5V) or ASM3 (+/-10V)
- 2 LLC (low level command)



- Discrete Interface terminal:
 μ C



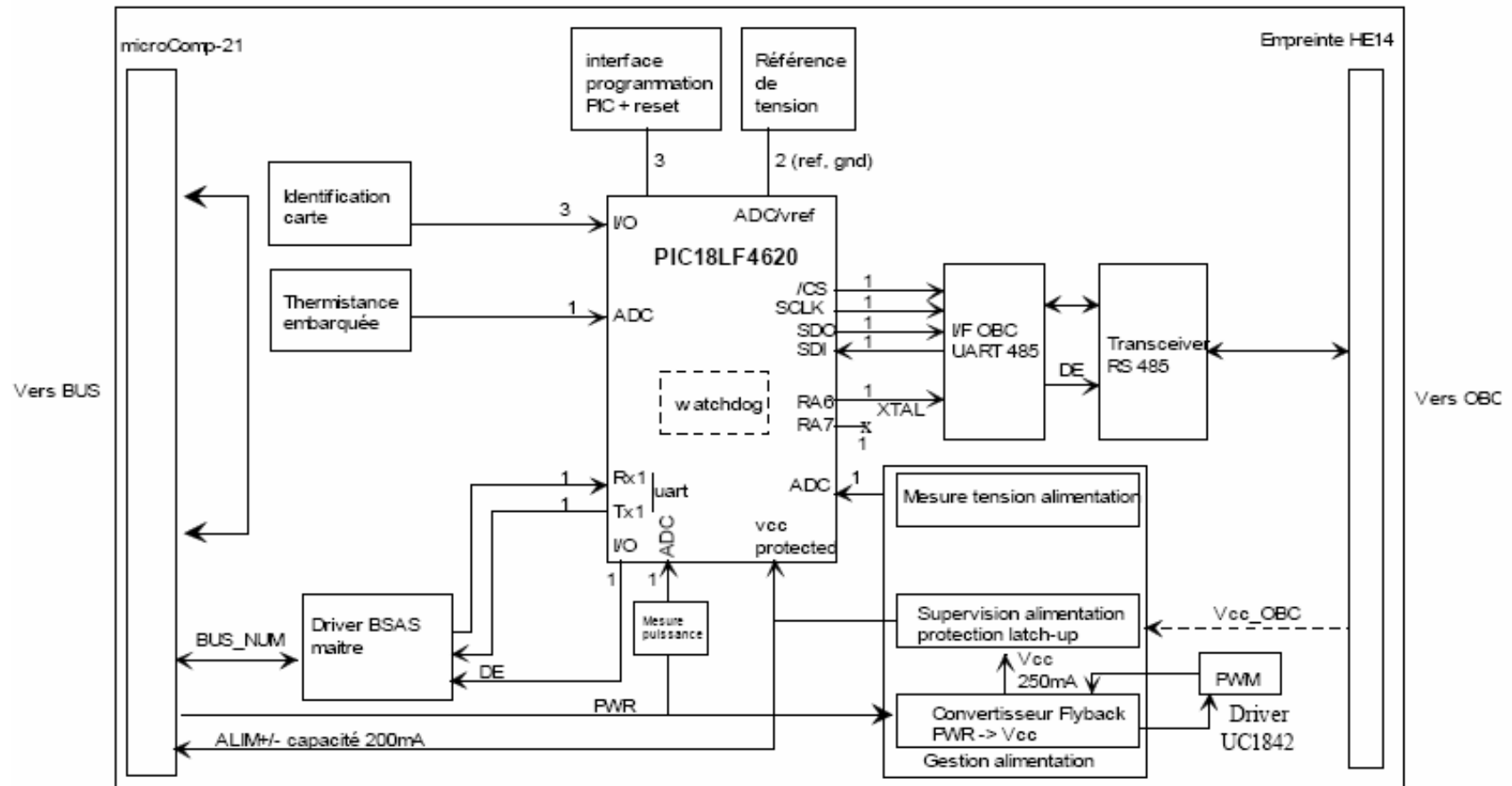
Top view

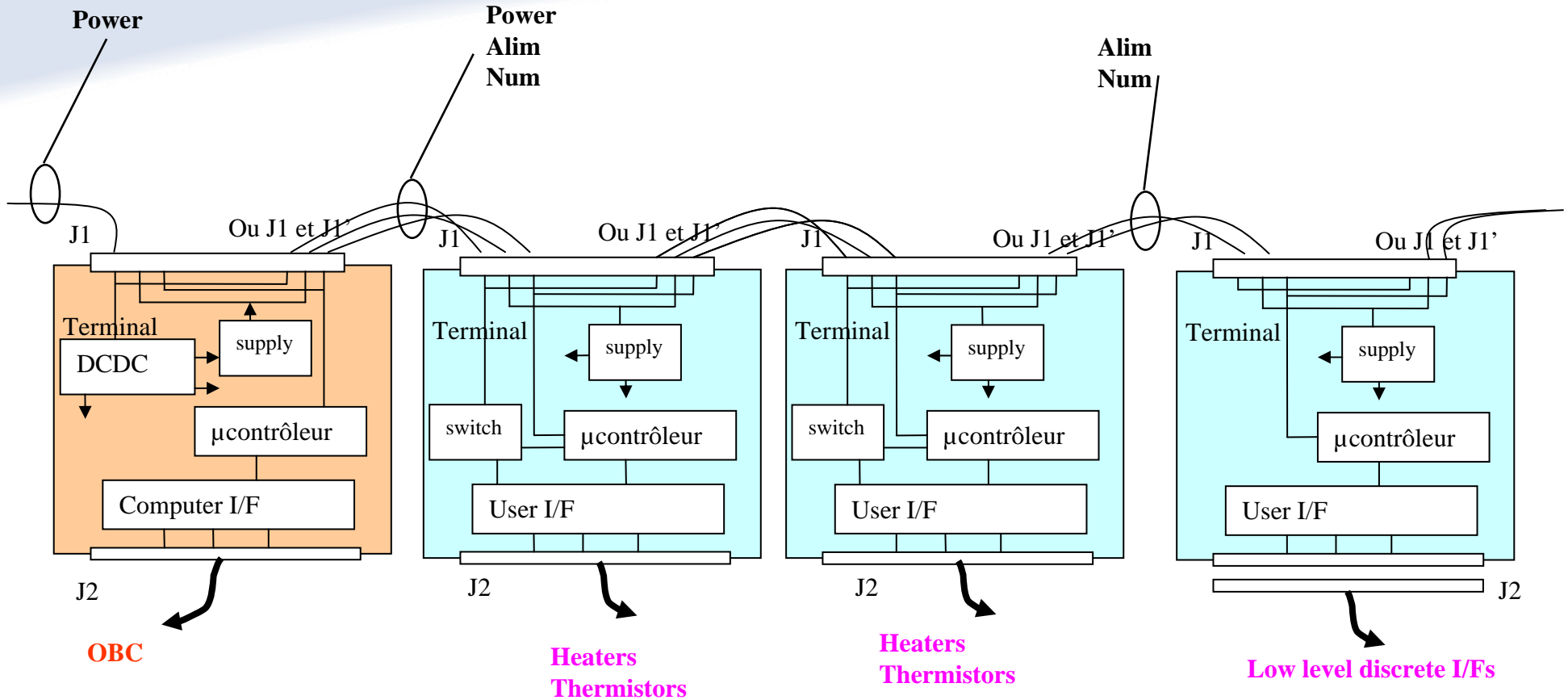


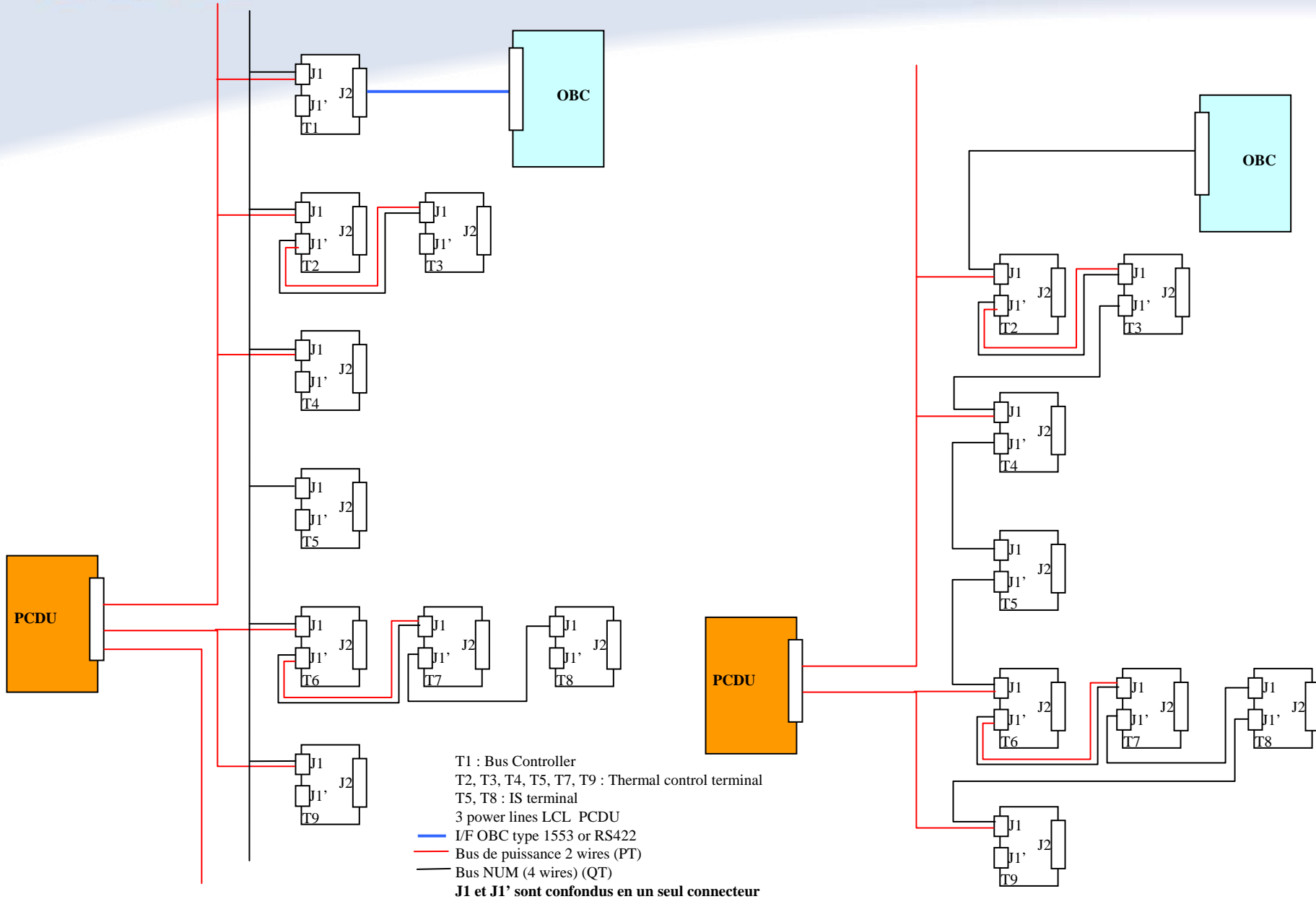
Bottom view

■ Bus Controller internal architecture :

- ◆ Internal DCDC converter : power supply all the terminals
- ◆ Internal UART for OBC interface
- ◆ 1553 I/F evaluated (but not bread-boarded)



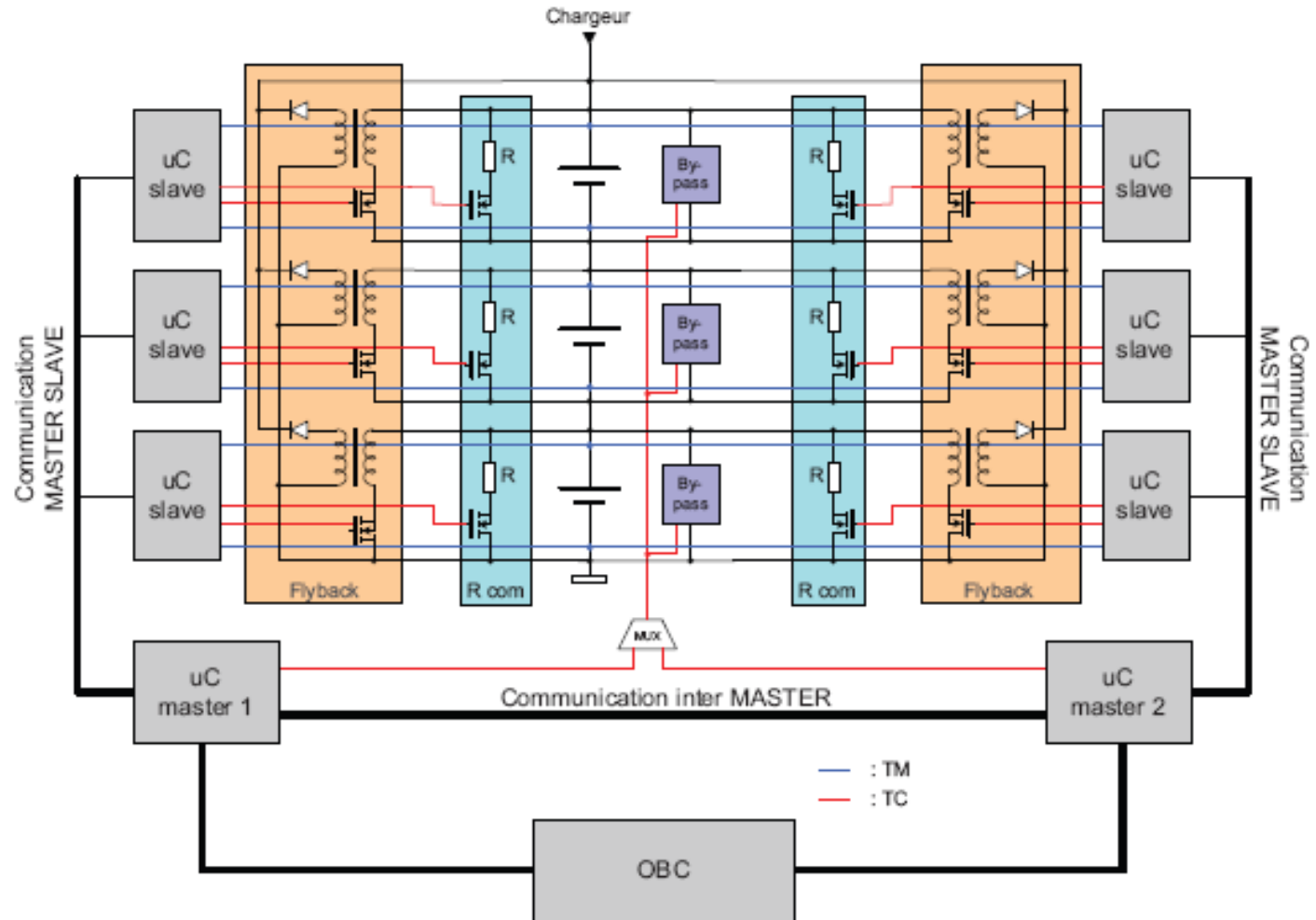




■ LIBBE : Lithium-ion Battery Balancing Electronic

LIBBE architecture :

- Redounded architecture
- Master microcontroller
- Slave microcontrollers (one per Li-Ion cell)
- Evaluation of two methods of cell balancing : switched resistor or Flyback
- By-Pass commands
- Communication busses



■ Advantage of Microcontroller for LIBBE :

- ◆ Microcontroller allows to reduce electronic circuit with smart functions on each battery cell
- ◆ Data bus communication between battery cells using internal microcontroller UART
- ◆ Need to adapt DC cell voltages on the data bus by capacitor coupling
- ◆ Possibilities to adapt balancing algorithms for a large type of Li-Ion batteries
- ◆ Microcontroller supply compatible with Li-ion cell voltage range
- ◆ Microcontroller with low consumption available

■ Master microcontroller main functions:

- ◆ **UART : interface RS485 Manchester bi-phase with capacitor coupling on master/slave communication bus**
- ◆ **SPI : Interfaces between the 2 redundant master microcontrollers**
- ◆ **I/O : OBC interface via RS422 links**
- ◆ **I/O : By-Pass commands**
- ◆ **ADC : battery voltage monitoring, temperature, internal voltages**

■ Microcontroller reference :

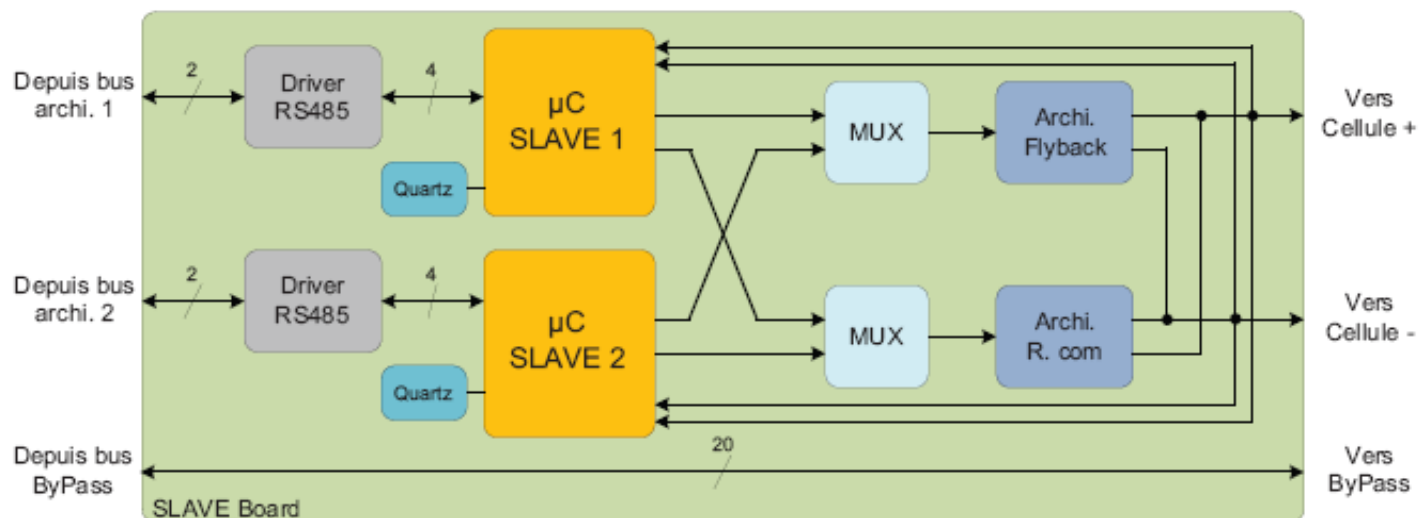
- ◆ **PIC18LF2520 : breadboard**
- ◆ **PIC18LF2620 compatible (see MYRIADE OBC, TCSBUS, Space studies)**

■ Slave microcontroller main functions :

- ◆ UART : interface RS485 Manchester biphas with capacitor coupling on master/slave communication bus
- ◆ PWM I/O : switch command of the balancing system
- ◆ ADC : cell voltage monitoring, reference voltage

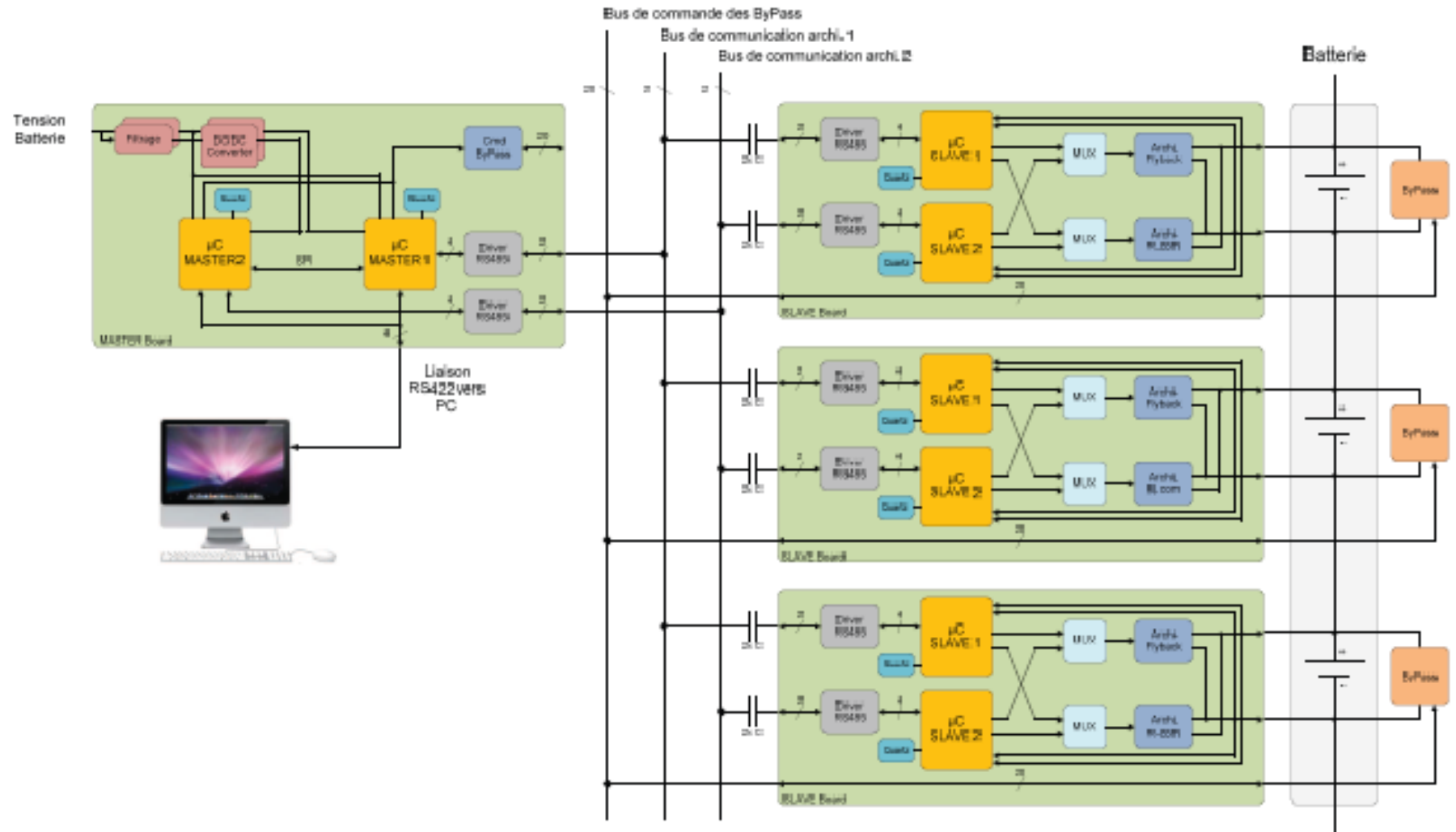
■ Microcontroller reference :

- ◆ PIC18LF2520 : breadboard
- ◆ PIC18LF2620 compatible (see MYRIADE OBC, TCSBUS, Space studies)
- ◆ Power management function : leakage current minimization on the Li-Ion cell (0.5 μ A in sleep mode)
- ◆ Supply voltage from 2V to 5.5V : version LF

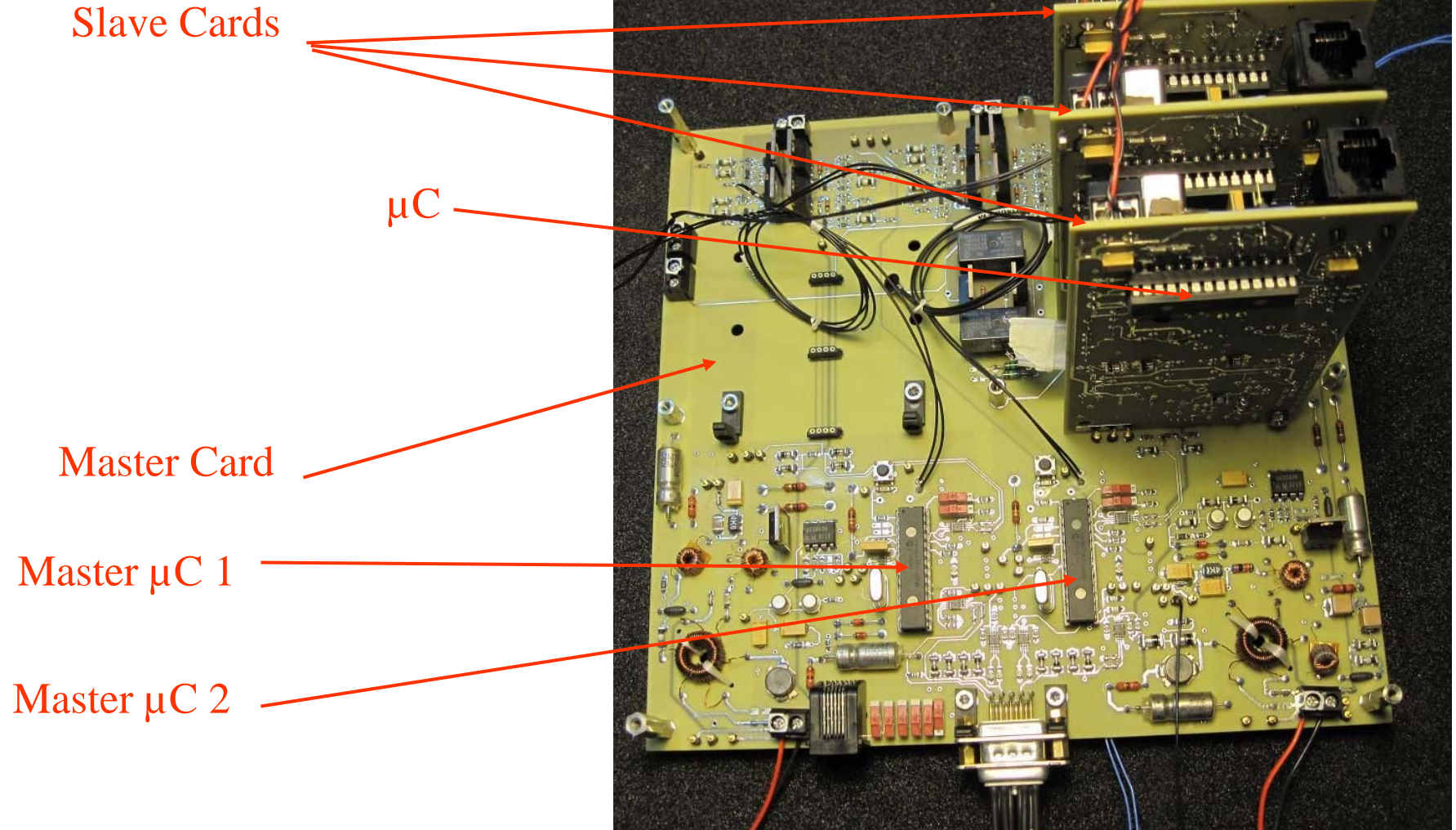


■ General implementation of the breadboard :

- ◆ Test on going



■ General implementation of the breadboard :



■ Advantages of Microcontrollers :

- ◆ Very high integration and small electronics
- ◆ Easy to develop
- ◆ Smart functions near utilization (acquisition, filtering, regulation, timing,...)
- ◆ No expensive

■ Drawbacks :

- ◆ Radiation tolerance to be tested
- ◆ Need to be protected against SEE, latch-up

■ Application :

- ◆ Low cost projects : MYRIADE...
- ◆ COTS